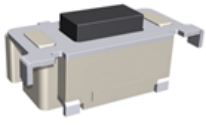




LTEM NO.: TS-1112 (Three D)
(L7.8mm × W3.5mm × H3.55mm TACT-SWITCH)



Technical parameter

PROJECT	LEVEL	A[better product]		B[average product]	
Electrical Properties	Contact Rating	50mA, 24V DC			
	Initial Contact Resistance	30mΩ max.		50mΩ max.	
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC		
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut		
	Durable Performance	There No Load	100,000 Cycles		75,000 Cycles
Rated Load		80,000 Cycles		50,000 Cycles	
Storage temp.		-25℃~+75℃(Operating Temp:)			

贴片安装 SMT

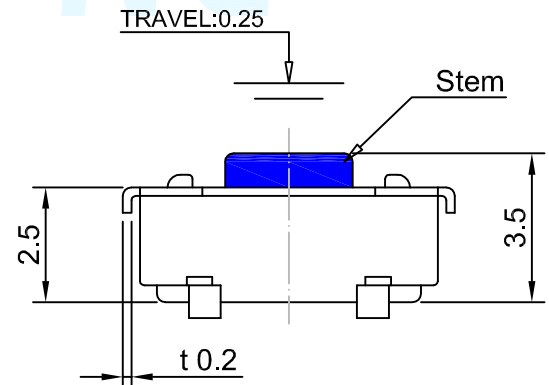
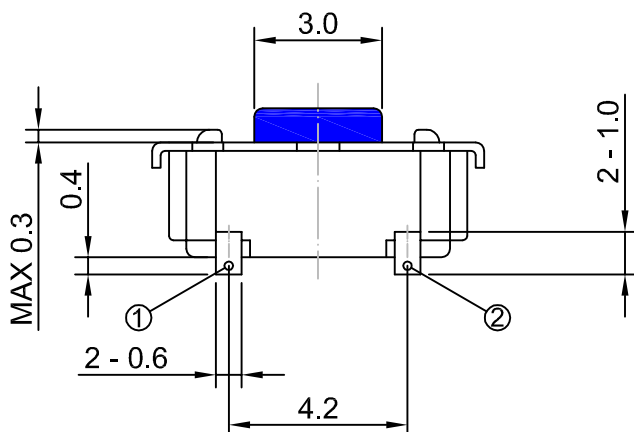
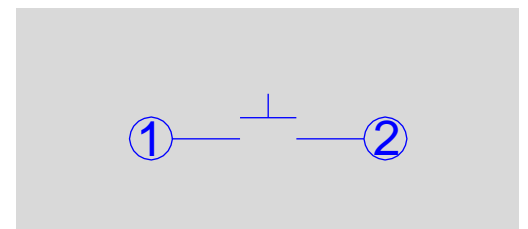
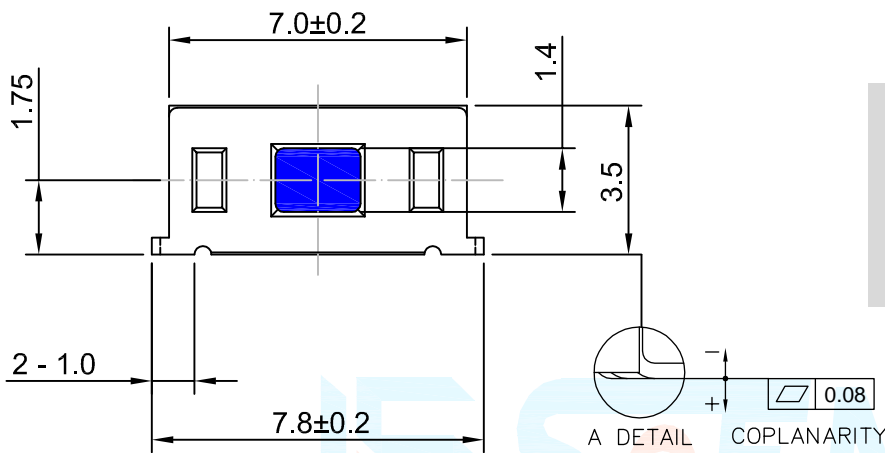
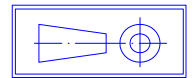
侧操作 LATERAL

精密部品 NICETY

可靠 STABILIZE

適合環保 RoHS

Unit:mm



Operating Force	Inward	2. 6N. (1N.=100gram-force)	Solder-ability (Max.)	
	Exiting	2. 0N. (1N.=100gram-force)	IR Reflow:255°C, 5sec.	Manual :350°C, 3sec.

DECIMALS	ANGLES
.X :±0.20	X.° :±1.5°
.XX :±0.10	X.X° :±1.0°
.XXX :±0.05	.XXX° :±0.5°

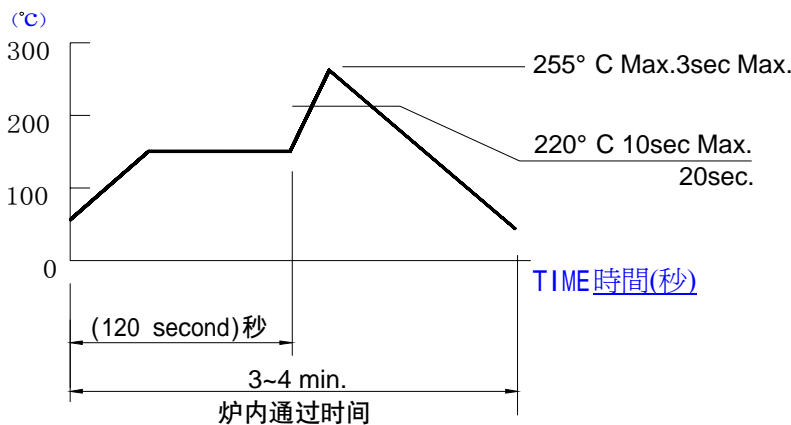
Material declaration



Material declaration		
No.	NAME	Description
① A	拨柄	LCP (Black)热塑性
② B	基座	LCP (Black)热塑性
③ C	盖板	SUS 不锈钢 Q235-A
④ D	簧片	镀银&不锈钢 SUS304
⑤ E	嵌件	镀银&黄铜

Please practice according to below condition:

- (1) Preheat :150 °C 90-120s
- (2) Soldering heat : 255 °C Max 10S.
- (3) Immersion depth: Up to the surface of the board



■ 手焊接时

项目	条件
焊接温度	350°C max.
连续焊接时间	3s max.
焊剂斗容量	60W max.

■ 自动浸焊时

项目	条件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷 电路板焊接面的周围温度 100°C max.
预热温度时间	60s max.
焊接温度	260°C max.
焊接浸渍时间	5s max.
焊接次数	2次以下

本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。
Products do not belong to

注記 NOTICE

1. 碩方公司擁有最終解釋權; The company reserves the right of final interpretation;
2. 文件禁止外洩、轉載; Leaked and reproduced prohibited;
3. 未經授權修改無效。Modify is invalid.

運送時本產品不要直接與水、酸鹼性化學物質接觸,或放置於含有以上氣體環境中,並且需要注意會有滑落、側翻的危險發生; 運輸過程中不能有碰撞或者擠壓,須保證溫度與濕度適中 [常溫 25°C,濕度在 50°C 以內],不可導致材料變形或氧化。